

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,833,727 B2
APPLICATION NO. : 10/803294
DATED : December 21, 2004
INVENTOR(S) : Farnworth et al.

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

- Col. 1, line 57, delete "circuitry" after "grated" and insert --circuitry--.
- Col. 1, line 64, delete "fabricator" after "chip" and insert --fabrication--.
- Col. 2, line 23, delete "search" after "or" and insert --scratch--.
- Col. 3, line 16, delete "or" before "engaging" and insert --of--.
- Col. 3 line 59, delete "vet" after "with" and insert --yet--.
- Col. 3, line 61, delete "packs on a semiconductor Substrate having Integrated" before "cir-" and insert -- pads on a semiconductor substrate having integrated--.
- Col. 4, line 30, insert --in-- after "lines".
- Col. 4, line 33, delete "s5" after "such".
- Col. 4, line 34, delete "tie" after "within" and insert --the--.
- Col. 4, line 36, delete "test" after "for" and insert --test--.
- Col. 4, line 40, delete "es" after "blocks/lines".
- Col. 4, line 43, delete "entire" before "with" and insert --entirely--.
- Col. 4, line 58, delete "trough H2O" before "while" and insert --through H₂O--.
- Col. 4, line 61, delete "stepping" after "such" and insert --stripping--.
- Col. 4, line 66, insert --HF-- after "temperature".
- Col. 5, line 13, delete "etc." after "isotropic" and insert --etch--.
- Col. 5. line 23, delete "numbed" after "are" and insert --numbered--.
- Col. 5, line 30, delete "sand" after "tip 58" and insert --and--.
- Col. 5, line 36, delete "apparatus." after "ing" and insert --apexes--.
- Col. 5, line 57, delete "conducted" after "be" and insert --conducted--.
- Col. 5, line 60, delete "rip" after "to" and insert --tip--.
- Col. 5, line 61, delete "deed arid" after "microns" and insert --deep and--.
- Col. 5, line 67, delete circuit" after "appropriate" and insert --circuitry--.
- Col. 6, line 7, delete "step" after "applies" and insert --atop--.
- Col. 6, line 11, delete "projection" after "exposed" and insert --projecting--.
- Col. 6, line 20, delete "11" after "substrate" and insert --12--.
- Col. 6, line 23, delete "desorption" before "only" and insert --deposition--.
- Col. 6, line 36, delete "photoresist:" after "provide" and insert --photoresist--.
- Col. 6, line 46, delete "tested" after "being" and insert --tested--.
- Col. 6, line 56, delete "or" after "confines" and insert --of--.
- Col. 6, line 60, delete "on-half" after "approximately" and insert --one-half--.

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Col. 7, line 15, delete "is" after "electrically".
Col. 7, line 18, delete "the" after "is" and insert --then--.
Col. 7, line 25, delete "electrodes as" after "as" and insert --electroless--.
Col. 7, line 30, delete "~~17~~" after "FIG." and insert --17--.
Col. 7, line 36, delete "electrodes" after "which" and insert --electroless--.
Col. 7, line 42, delete "electrodes" before "deposition" and insert --electroless--.
Col. 7, line 47, delete "he" after "rendering" and insert --the--.
Col. 7, line 52, delete layer." After "ation" and insert --layer--.

Signed and Sealed this

First Day of August, 2006

A handwritten signature in black ink, reading "Jon W. Dudas". The signature is stylized, with a large, looped initial "J" and a distinct "D" at the end.

JON W. DUDAS
Director of the United States Patent and Trademark Office